MT53D1024M32D4DT-046 WT

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Orderable parts

MT53D1024M32D4DT-046 WT:D

Specs

Chipset Validation	N/A
Cycle Time	0.46ns
Data Rate	DDR4-4266
Density	32Gb
FBGA Code	D9WQG
Op. Temp.	-25C to +85C
Part Status	Production

Data Sheets

RoHS

REACH Statement

Simulation Models

Technical Notes

TN-00-08: Thermal Applications

Product Longevity Program	No
Product Longevity Program Start Date	N/A
Technology	LPDDR4
Width	x32

This document describes considerations in thermal applications for Micron memory devices, including thermal impedance, thermal resistance, junction temperature, operating temperature, memory reliability, reliability modeling, device reliability, and high-temperature electronics.

File Type: PDF

Updated: 2020-03-25

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TN-ED-04: GDDR6 Design Guide

This technical note is designed to help designers implement GDDR6 as an off-the-shelf memory with established packaging, handling and testing. It outlines best practices for signal and power integrity, as well as standard GDDR6 DRAM features, to help system designs achieve the high data rates offered by GDDR6.

File Type: PDF

Updated: 2018-07-30

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Customer Service Notes

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